

# RD3P05BAT

### Pch -100V -50A Power MOSFET

V <sub>DSS</sub>	-100V
R <sub>DS(on)</sub> (Max.)	41mΩ
I <sub>D</sub>	±50A
P <sub>D</sub>	101W

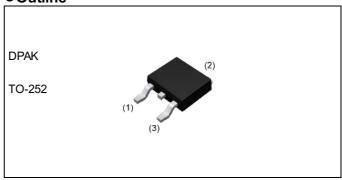
# ●Features

- 1) Low on resistance
- 2) High power small mold package
- 3) Pb-free plating; RoHS compliant
- 4) 100% Rg and UIS tested
- 5) Halogen free

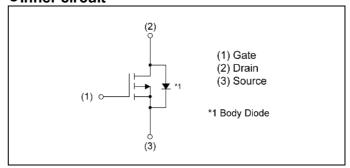
### Application

Switching

### Outline



### •Inner circuit



Packaging specifications

● F ackaç	Jing specifications	
	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	16
	Quantity (pcs)	2500
	Taping code	TL1
	Marking	RD3P05BAT

### ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		$V_{DSS}$	-100	V
Continuous drain current	V <sub>GS</sub> = -10V	I <sub>D</sub> *1	±50	Α
Pulsed drain current	I <sub>DP</sub> *2	±100	Α	
Gate - Source voltage		V <sub>GSS</sub>	±20	V
Avalanche current, single pulse		I <sub>AS</sub> *3	-25	Α
Avalanche energy, single pulse		E <sub>AS</sub> *3	44	mJ
Power dissipation		P <sub>D</sub> *1	101	W
Junction temperature		T <sub>j</sub>	150	°C
Operating junction and storage terr	T <sub>stg</sub>	-55 to +150	°C	

### ●Thermal resistance

Parameter	Symbol	Values			Linit
		Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *1	-	1	1.23	°C/W

### ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davamatav	Cymah al	Canditions		Values		l lait	
Parameter	Symbol Conditions –		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = -1mA$		-100	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_i} I_D = -1 \text{mA}$ referenced to 25°C		-	-68	-	mV/°C	
Zero gate voltage drain current	$I_{DSS}$ $V_{DS} = -100V, V_{GS} = 0V$		-	-	-1	μА	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±100	nA	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = -1mA$	-2.0	-	-4.0	V	
Gate threshold voltage temperature coefficient	$\frac{\DeltaV_{GS(th)}}{\DeltaT_j}$	I <sub>D</sub> = -1mA referenced to 25°C	-	5.1	-	mV/°C	
Static drain - source	R <sub>DS(on)</sub> *4	V <sub>GS</sub> = -10V, I <sub>D</sub> = -25A	-	32	41	O	
on - state resistance		V <sub>GS</sub> = -6V, I <sub>D</sub> = -25A	-	35	46	mΩ	
Gate resistance	R <sub>G</sub> f = 1MHz, open drain		-	7.2	-	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>  *4	V <sub>DS</sub> = -5V, I <sub>D</sub> = -25A	20	-	-	S	

<sup>\*1</sup> T<sub>c</sub>=25°C, Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw ≤ 10µs, Duty cycle ≤ 1%

<sup>\*3</sup> L  $\simeq$  0.1mH, V<sub>DD</sub> = -50V, R<sub>G</sub> = 25 $\Omega$ , Starting T<sub>i</sub> = 25 $^{\circ}$ C Fig.3-1,3-2

<sup>\*4</sup> Pulsed

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

Dorameter	Cumbal	Conditions		Lloit			
Parameter	Symbol Conditions —		Min.	Тур.	Max.	Unit	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	4620	-		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = -50V	-	200	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	1	160	1		
Turn - on delay time	t <sub>d(on)</sub> *4	$V_{DD} \simeq -50V, V_{GS} = -10V$	1	28	1		
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = -25A	-	60	-		
Turn - off delay time	t <sub>d(off)</sub> *4	$R_L \simeq 2\Omega$	-	235	-	ns	
Fall time	t <sub>f</sub> *4	$R_G = 10\Omega$	-	145	-		

## • Gate charge characteristics $(T_a = 25^{\circ}C)$

Doromotor	Cymah al	ymbol Conditions		Values			l limit	
Parameter	Symbol			Min.	Тур.	Max.	Unit	
T. ( )	O *4		V <sub>GS</sub> = -10V	-	110	-		
Total gate charge	$Q_g^{*4}$	$Q_g$	V <sub>DD</sub> ≃ -50V		-	68	-	<b>"</b> C
Gate - Source charge	Q <sub>gs</sub> *4	I <sub>D</sub> = -50A	V <sub>GS</sub> = -6V	-	21	-	nC	
Gate - Drain charge	Q <sub>gd</sub> *4			-	34	-		

### ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions		Unit		
Parameter	Symbol	ool Conditions		Тур.	Max.	Offic
Continuous forward current	I <sub>S</sub>	T <sub>a</sub> = 25°C	1	-	-50	Α
Pulse forward current	I <sub>SP</sub> *2	1 <sub>a</sub> - 25 C	-	-	-100	Α
Forward voltage	V <sub>SD</sub> *4	$V_{GS} = 0V, I_{S} = -50A$	-	-	-1.2	V
Reverse recovery time	t <sub>rr</sub> *4	I <sub>S</sub> = -50A, V <sub>GS</sub> =0V	-	45	-	ns
Reverse recovery charge	Q <sub>rr</sub> *4	di/dt = 100A/μs	-	140	-	nC

Fig.1 Power Dissipation Derating Curve

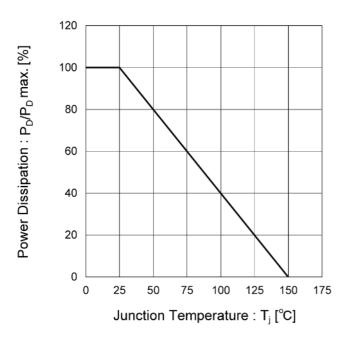
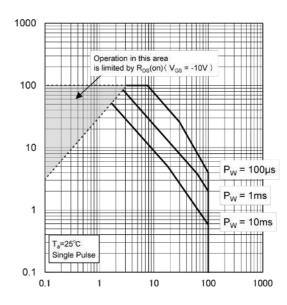


Fig.2 Maximum Safe Operating Area



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

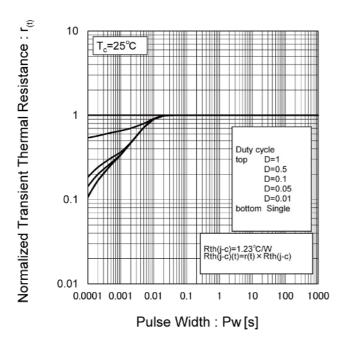
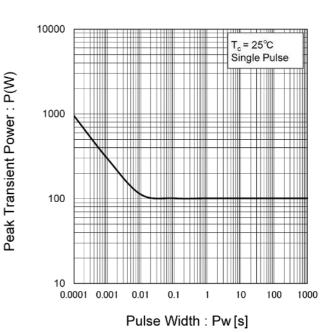


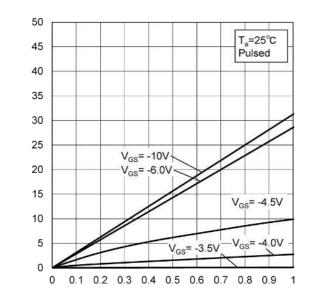
Fig.4 Single Pulse Maximum Power Dissipation



Drain Current : I<sub>D</sub> [A]

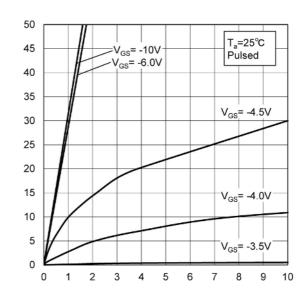
### • Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)



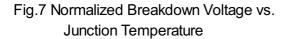
Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.6 Typical Output Characteristics(II)



Drain Current: Ip [A]

Drain - Source Voltage : V<sub>DS</sub> [V]



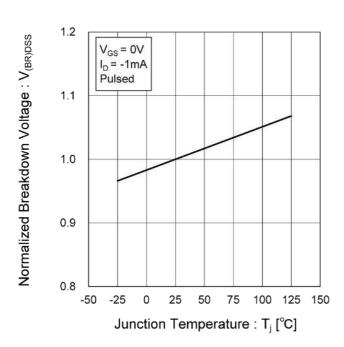


Fig.8 Typical Transfer Characteristics

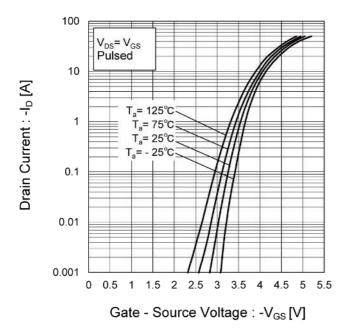


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

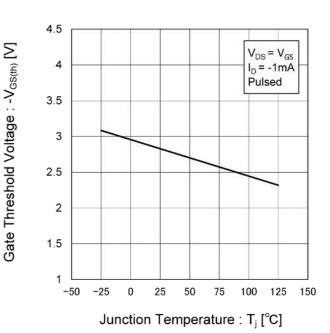
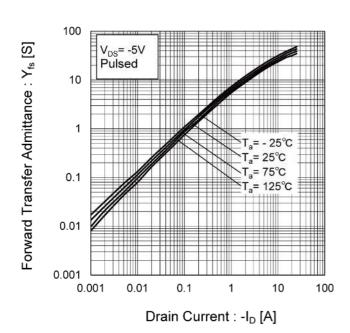


Fig.10 Forward Transfer Admittance vs.
Drain Current



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Fig.11 Drain Current Derating Curve

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

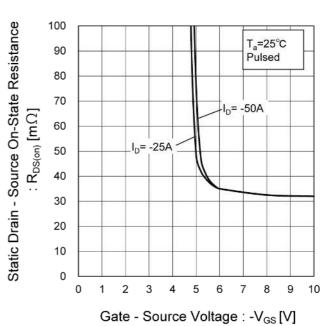
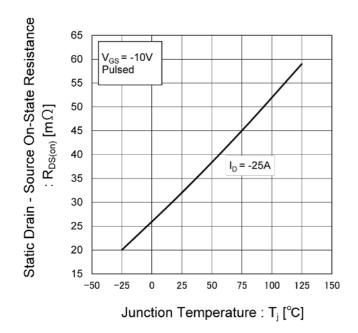


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature



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Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I)

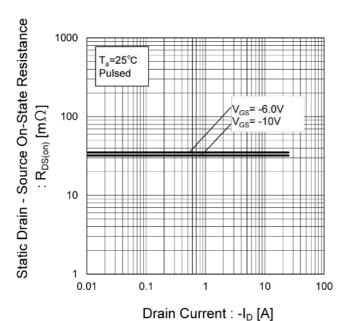


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)

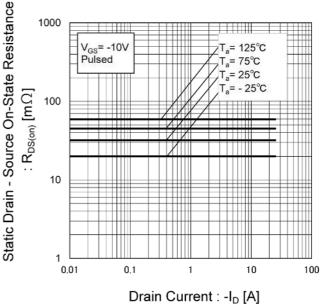


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)

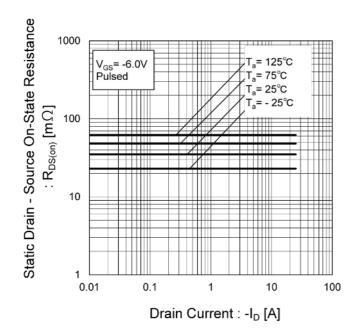
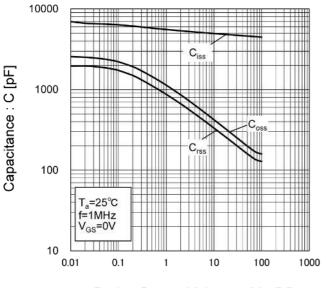


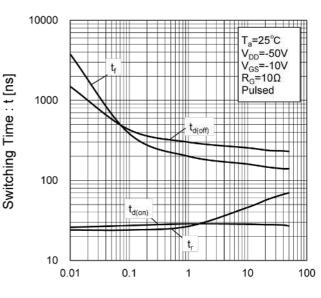
Fig.17 Typical Capacitances vs.

Drain - Source Voltage



Drain - Source Voltage : -V<sub>DS</sub> [V]

Fig.18 Switching Characteristics



Drain Current: -ID [A]

Fig.19 Typical Gate Charge

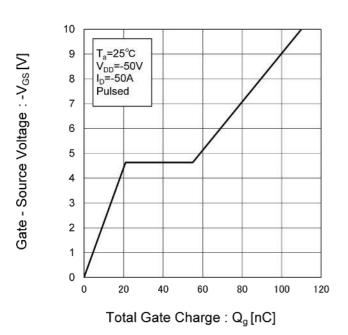
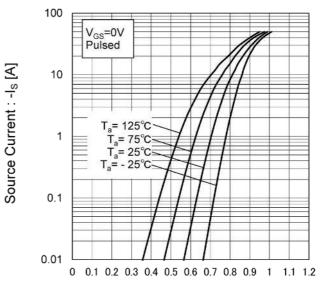


Fig.20 Source Current vs.
Source Drain Voltage



Source - Drain Voltage : -V<sub>SD</sub> [V]

### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

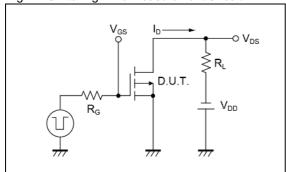


Fig.2-1 Gate Charge Measurement Circuit

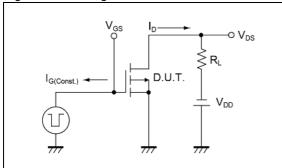


Fig.3-1 Avalanche Measurement Circuit

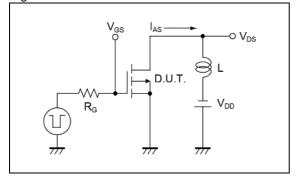


Fig.1-2 Switching Waveforms

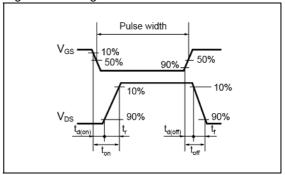


Fig.2-2 Gate Charge Waveform

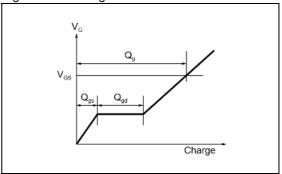
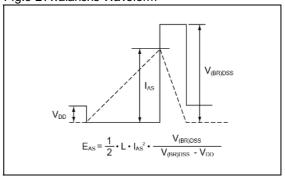
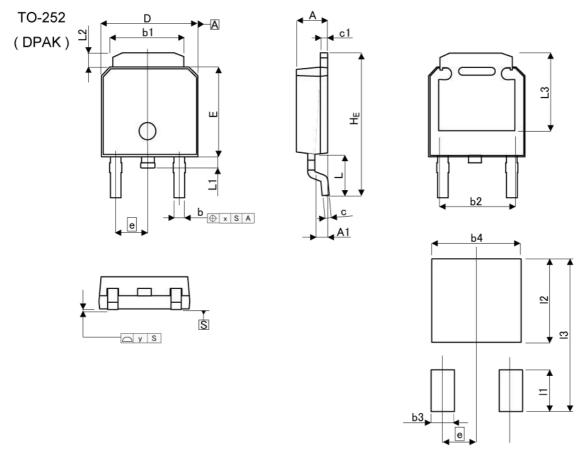


Fig.3-2 Avalanche Waveform



### Dimensions



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM -	MILIME	ETERS	INCHES		
DIIVI	MIN	MAX	MIN	MAX	
Α	2.20	2.40	0.087	0.094	
A1	0.70	1.10	0.028	0.043	
b	0.60	0.90	0.024	0.035	
b1	5.20	5.50	0.205	0.217	
b2	4.	80	0.1	89	
С	0.40	0.60	0.016	0.024	
c1	0.40	0.60	0.016	0.024	
D	6.40	6.80	0.252	0.268	
е	2.	30	0.0	91	
E	6.00	6.40	0.236	0.252	
HE	9.40	10.40	0.370	0.409	
L	2.	90	0.114		
L1	0.60	1.00	0.024	0.039	
L2	0.70	1.30	0.028	0.051	
L3	5.	30	0.209		
Х	-	0.25	(#)	0.010	
у	-	0.10	4577	0.004	
DIM -	MILIME	ETERS	INC	HES	
	MIN	MAX	MIN	MAX	
b3	#	1.15	7#8	0.045	
b4	-	5.55	A.T.O.	0.219	
11	-	2.77	\$( <del>4</del> 3)	0.109	
12	-	5.50	350	0.217	
13	2	10.40	-	0.409	

Dimension in mm/inches

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JAPAN	USA	EU	CHINA
CLASSⅢ	CL ACCTI	CLASS II b	СГУССШ
CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

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  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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